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Part Number: [0739440001](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, Guide Post Location A, Polarizing Key Position A, 72 Circuits

Documents:

[3D Model](#) [Packaging Specification PK-70873-0818 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73670-9999 \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

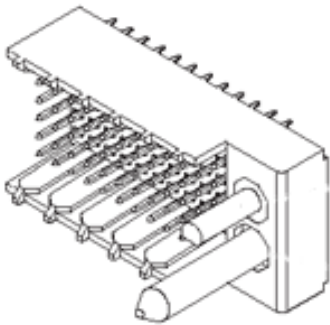
General

Product Family Backplane Connectors
Series [73944](#)
Application Backplane
Component Type PCB Header
Overview [HDM Backplane Connector System](#)
Product Name HDM
UPC 800755030969

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part Yes
Keying to Mating Part Yes
Material - Metal Phosphor Bronze, Stainless Steel
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 2.00mm
PCB Locator Yes
PCB Retention None
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable No
Surface Mount Compatible (SMC) No
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole

Electrical



Series image - Reference only

EU ELV

Not Reviewed

EU RoHS

Not Reviewed

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

For more information, please visit [Contact US](#)

China RoHS

China ROHS Not Reviewed
ELV Not Reviewed
RoHS Phthalates Not Reviewed

Search Parts in this Series

[73944](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard Receptacle. [73780](#) HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

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